

TechConnect Ventures

Sprint Challenge Brief:

Sustainable, High-Performance Foams for Packaging Applications

Sprint Submissions Closed

BACKGROUND

On behalf of multiple Fortune 2000 organizations, TechConnect Ventures is issuing this call for innovations in the area of sustainable foam materials. Foams used in packaging and related product applications must adhere to a diverse range of requirements including shock absorption, bracing, blocking, and moldability over a wide variety of shapes and sizes. Unfortunately, many high-performing foams require materials and/or manufacturing processes which do not meet the strict, growing demands for sustainability in the consumer, commercial and regulatory sectors.

REQUIREMENTS

TechConnect is seeking materials that can be used - or that can be developed and optimized for use in - packaging and related product applications. Solvers submitting an Entry should make efforts to address the following key focus areas in their Submission if applicable:

- Sourcing of materials/raw materials from bio-based or renewable materials
- Energy-efficiency of production
- Minimization of carbon footprint
- Reusability or recyclability
- Ease of disposal, including eco-friendly options such as compostability or biodegradation

In addition to the criteria above, you are highly encouraged to highlight any additional material characteristics or performance properties that differentiate your technology including, but not limited to: lightweighting, durability, cushioning, insulation (thermal, vibration, etc.), leak-resistance, and any other properties critical to packaging applications.

BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in an exclusive Innovation Opportunity Report that will be presented to our consortium of innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

Solvers are encouraged to review the Rules and Guidelines provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com